

Features

- Advanced Process Technology
- New Ultra Low On-Resistance
- 175°C Operating Temperature
- Fast Switching
- Repetitive Avalanche Allowed up to T_{jmax}
- Lead-Free, RoHS Compliant
- Automotive Qualified *

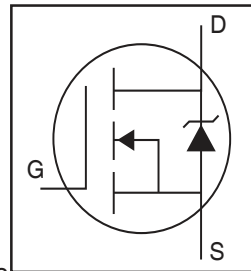
Description

Specifically designed for Automotive applications, this HEXFET® Power MOSFET utilizes the latest processing techniques to achieve extremely low on-resistance per silicon area. Additional features of this design are a 175°C junction operating temperature, fast switching speed and improved repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in Automotive applications and wide variety of other applications.

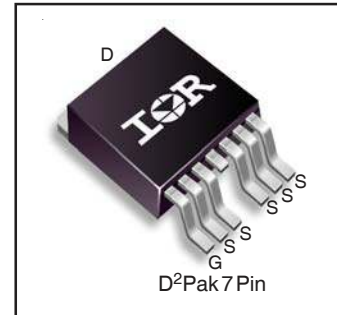
Applications

- Electric Power Steering (EPS)
- Battery Switch
- Start/Stop Micro Hybrid
- Heavy Loads
- DC-DC Applications

HEXFET® Power MOSFET



V_{DSS}		40V
$R_{DS(on)}$	typ.	1.0mΩ
	max.	1.3mΩ
I_D (Silicon Limited)		306A Ⓣ
I_D (Package Limited)		240A



G	D	S
Gate	Drain	Source

Base part number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
AUIRFS8407-7P	D2Pak-7PIN	Tube	50	AUIRFS8407-7P
		Tape and Reel Left	800	AUIRFS8407-7TRL
		Tape and Reel Right	800	AUIRFS8407-7TRR

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

Symbol	Parameter	Max.	Units
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Silicon Limited)	306 Ⓣ	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Silicon Limited)	216 Ⓣ	
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$ (Package Limited)	240	
I_{DM}	Pulsed Drain Current ②	1040	
$P_D @ T_C = 25^\circ\text{C}$	Maximum Power Dissipation	231	W
	Linear Derating Factor	1.5	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS} (Thermally limited)	Single Pulse Avalanche Energy ③	344	mJ
E_{AS} (tested)	Single Pulse Avalanche Energy Tested Value ⑩	508	
I_{AR}	Avalanche Current ②	See Fig. 14, 15, 24a, 24b	A
E_{AR}	Repetitive Avalanche Energy ②		mJ
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to + 175	°C
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	

HEXFET® is a registered trademark of International Rectifier.

*Qualification standards can be found at <http://www.irf.com/>

Thermal Resistance

Symbol	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ⑨⑩	—	0.65	°C/W
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount) ⑨	—	40	

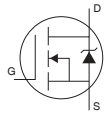
Static @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	40	—	—	V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient	—	0.035	—	V/°C	Reference to $25^\circ\text{C}, I_D = 1.0\text{mA}$ ②
$R_{DS(on)}$	Static Drain-to-Source On-Resistance	—	1.0	1.3	mΩ	$V_{GS} = 10V, I_D = 100A$ ⑤
$V_{GS(th)}$	Gate Threshold Voltage	2.2	—	3.9	V	$V_{DS} = V_{GS}, I_D = 150\mu A$
I_{DSS}	Drain-to-Source Leakage Current	—	—	1.0	μA	$V_{DS} = 40V, V_{GS} = 0V$
		—	—	150		$V_{DS} = 40V, V_{GS} = 0V, T_J = 125^\circ\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage	—	—	-100		$V_{GS} = -20V$
R_G	Internal Gate Resistance	—	2.2	—	Ω	

Dynamic @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

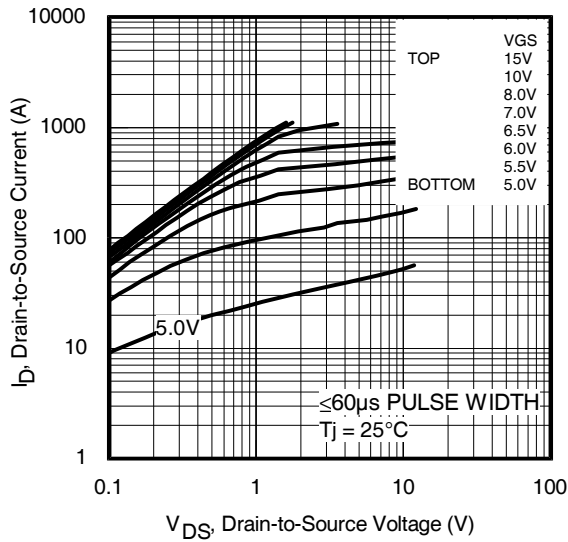
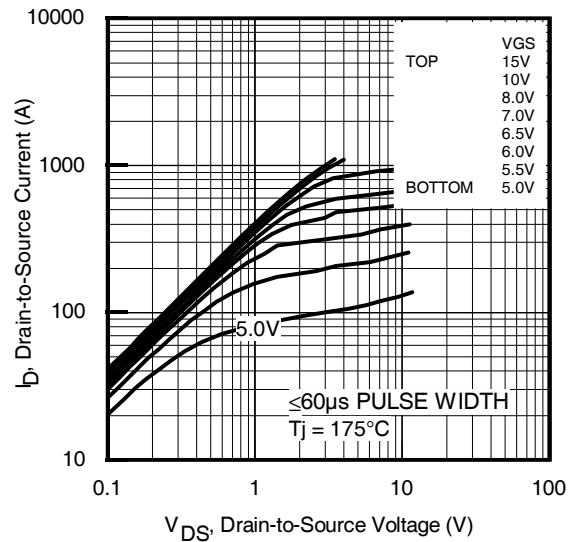
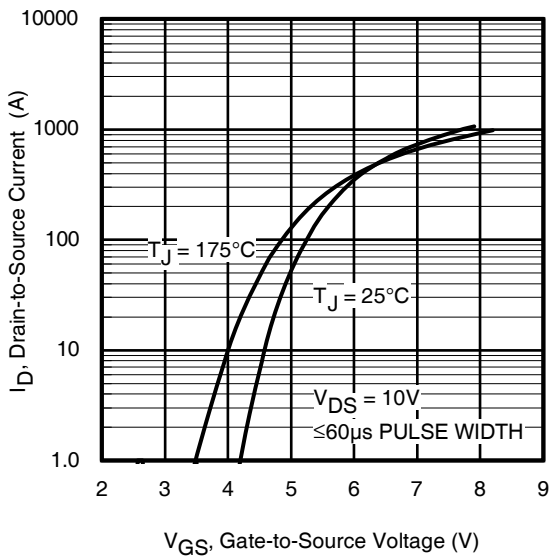
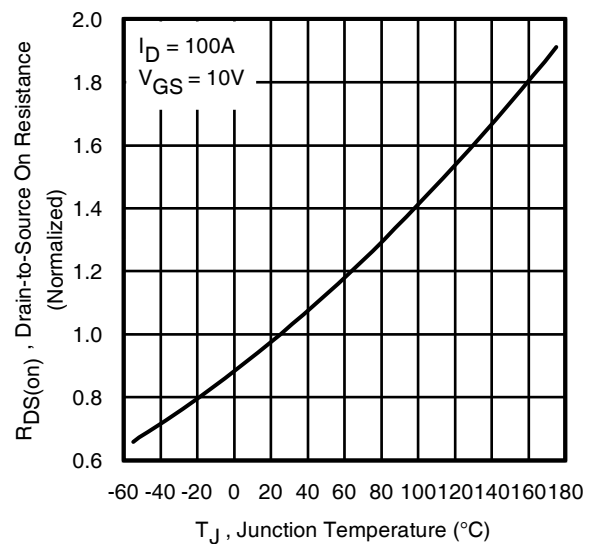
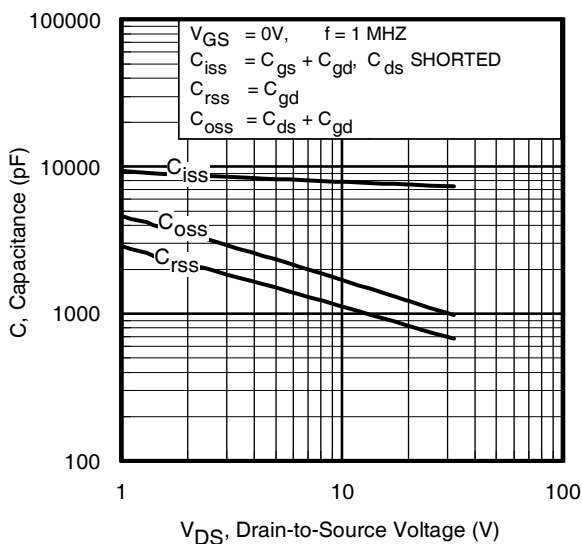
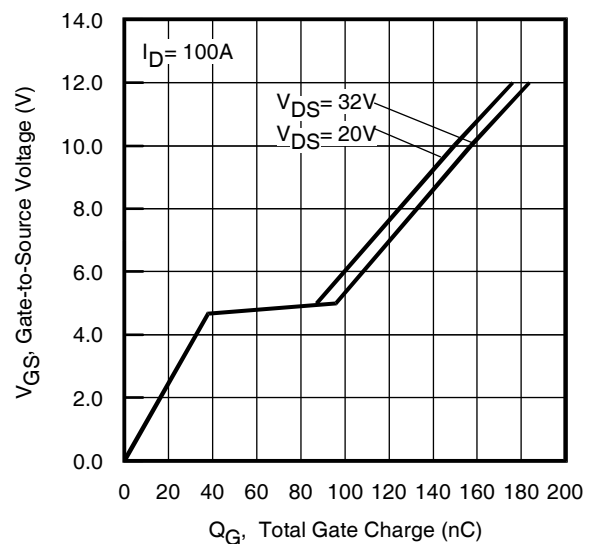
Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
gfs	Forward Transconductance	122	—	—	S	$V_{DS} = 10V, I_D = 100A$
Q_g	Total Gate Charge	—	150	225	nC	$I_D = 100A$ $V_{DS} = 20V$ $V_{GS} = 10V$ ⑤
Q_{gs}	Gate-to-Source Charge	—	41	—		
Q_{gd}	Gate-to-Drain ("Miller") Charge	—	51	—		
Q_{sync}	Total Gate Charge Sync. ($Q_g - Q_{gd}$)	—	99	—		
$t_{d(on)}$	Turn-On Delay Time	—	18	—	ns	$V_{DD} = 20V$ $I_D = 30A$ $R_G = 2.7\Omega$ $V_{GS} = 10V$ ⑤
t_r	Rise Time	—	62	—		
$t_{d(off)}$	Turn-Off Delay Time	—	78	—		
t_f	Fall Time	—	51	—		
C_{iss}	Input Capacitance	—	7437	—	pF	$V_{GS} = 0V$ $V_{DS} = 25V$ $f = 1.0\text{MHz}$ $V_{GS} = 0V, V_{DS} = 0V$ to $32V$ ⑦ $V_{GS} = 0V, V_{DS} = 0V$ to $32V$ ⑧
C_{oss}	Output Capacitance	—	1097	—		
C_{rss}	Reverse Transfer Capacitance	—	748	—		
$C_{oss\text{ eff. (ER)}}$	Effective Output Capacitance (Energy Related)	—	1314	—		
$C_{oss\text{ eff. (TR)}}$	Effective Output Capacitance (Time Related)	—	1735	—		

Diode Characteristics

Symbol	Parameter	Min.	Typ.	Max.	Units	Conditions
I_S	Continuous Source Current (Body Diode)	—	—	306 ①	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I_{SM}	Pulsed Source Current (Body Diode) ②	—	—	1040		
V_{SD}	Diode Forward Voltage	—	1.0	1.3	V	$T_J = 25^\circ\text{C}, I_S = 100A, V_{GS} = 0V$ ⑤
dv/dt	Peak Diode Recovery ④	—	3.5	—	V/ns	$T_J = 175^\circ\text{C}, I_S = 100A, V_{DS} = 40V$
t_{rr}	Reverse Recovery Time	—	37	—	ns	$T_J = 25^\circ\text{C}$ $V_R = 34V,$ $T_J = 125^\circ\text{C}$ $I_F = 100A$
		—	38	—		
Q_{rr}	Reverse Recovery Charge	—	34	—	nC	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$ $di/dt = 100A/\mu s$ ⑤
		—	36	—		
I_{RRM}	Reverse Recovery Current	—	1.8	—	A	$T_J = 25^\circ\text{C}$
t_{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

- ① Calculated continuous current based on maximum allowable junction temperature. Bond wire current limit is 240A. Note that current limitations arising from heating of the device leads may occur with some lead mounting arrangements. (Refer to AN-1140)
- ② Repetitive rating; pulse width limited by max. junction temperature.
- ③ Limited by T_{Jmax} , starting $T_J = 25^\circ\text{C}$, $L = 0.069\text{mH}$, $R_G = 50\Omega$, $I_{AS} = 100A$, $V_{GS} = 10V$. Part not recommended for use above this value.
- ④ $I_{SD} \leq 100A$, $di/dt \leq 1288A/\mu s$, $V_{DD} \leq V_{(BR)DSS}$, $T_J \leq 175^\circ\text{C}$.
- ⑤ Pulse width $\leq 400\mu s$; duty cycle $\leq 2\%$.
- ⑥ $C_{oss\text{ eff. (TR)}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- ⑦ $C_{oss\text{ eff. (ER)}}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .
- ⑧ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.
- ⑨ R_θ is measured at T_J approximately 90°C .
- ⑩ $R_{\theta JC}$ value shown is at time zero.


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics

Fig 3. Typical Transfer Characteristics

Fig 4. Normalized On-Resistance vs. Temperature

Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

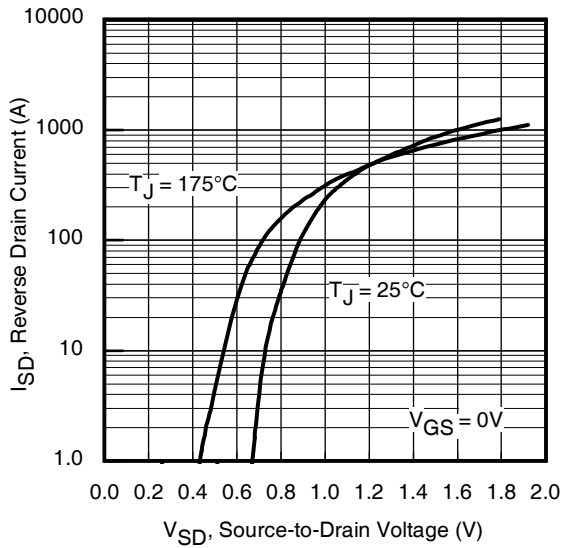


Fig 7. Typical Source-Drain Diode Forward Voltage

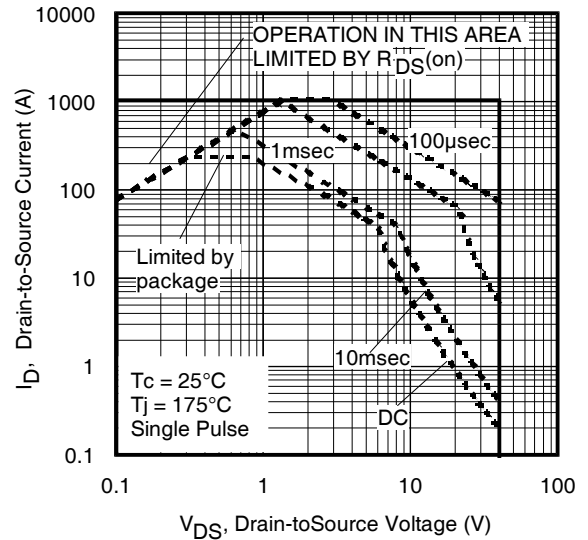


Fig 8. Maximum Safe Operating Area

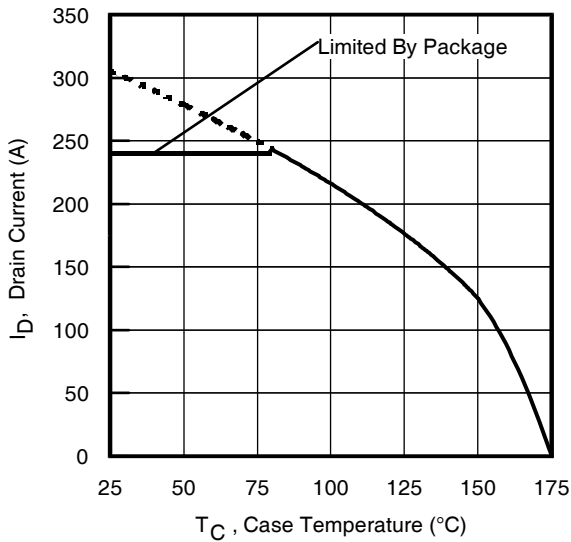


Fig 9. Maximum Drain Current vs. Case Temperature

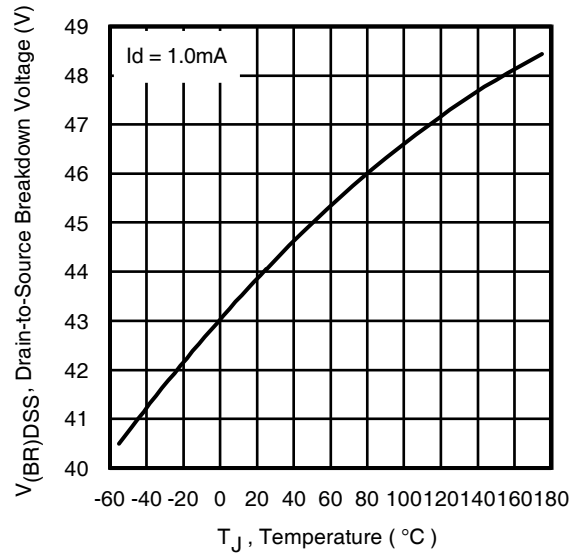


Fig 10. Drain-to-Source Breakdown Voltage

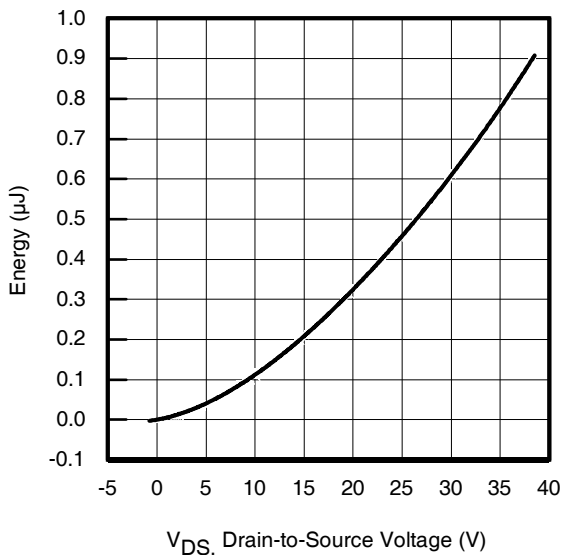


Fig 11. Typical C_{oss} Stored Energy

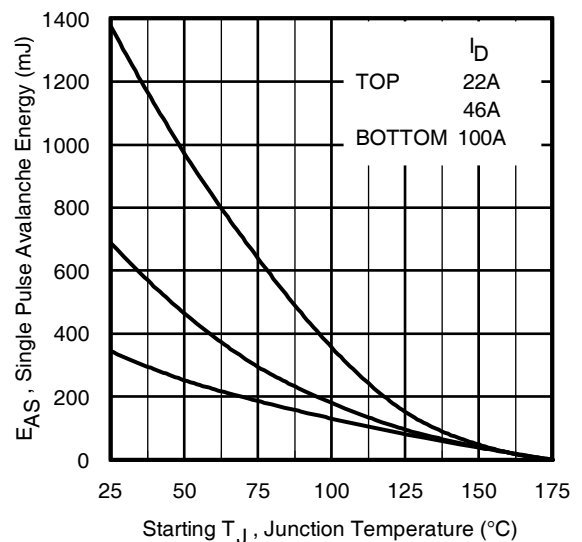
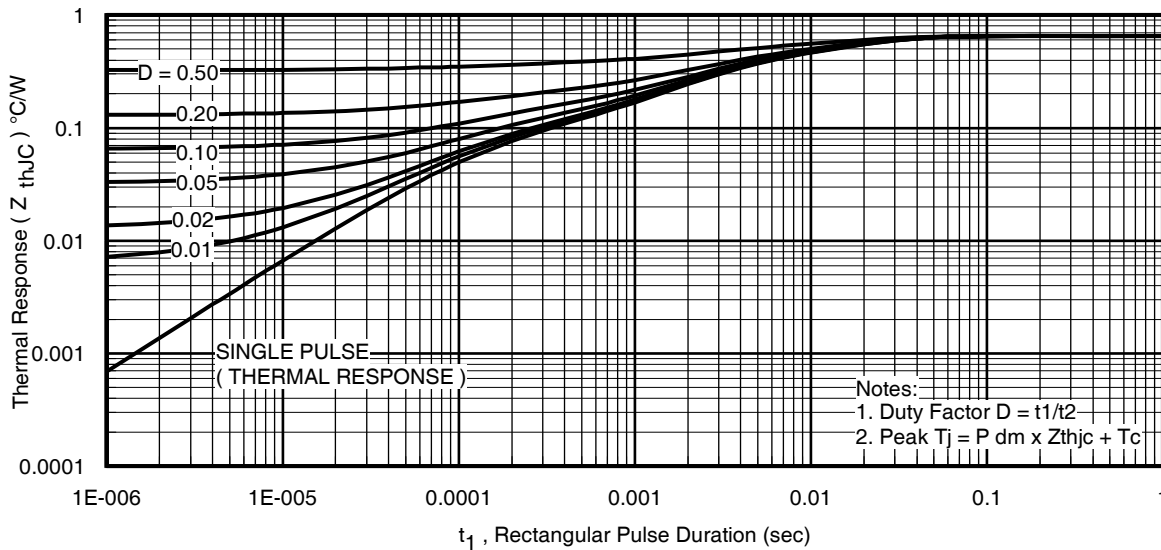
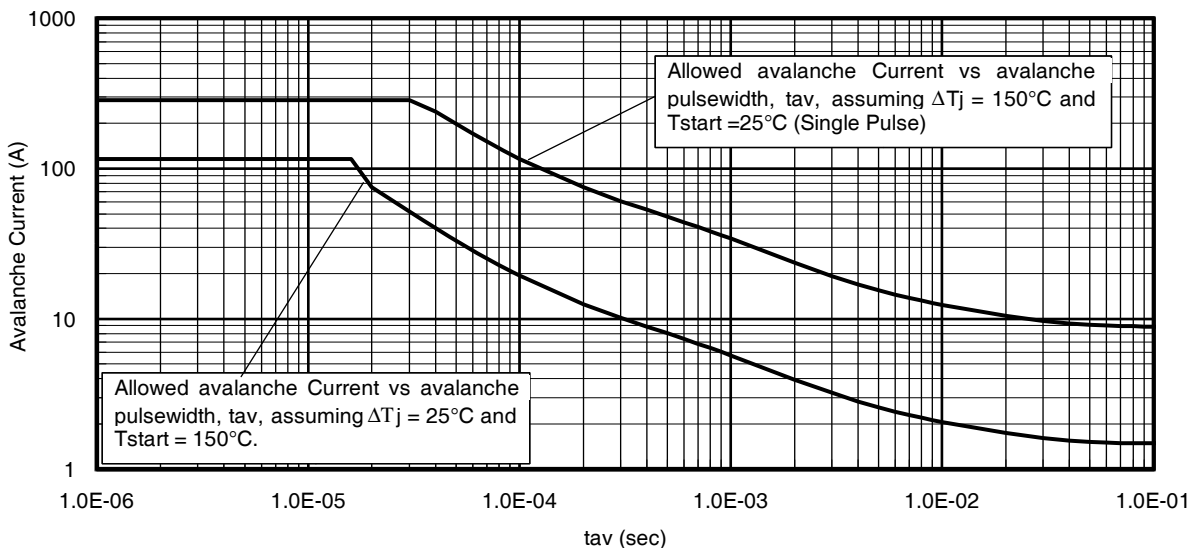
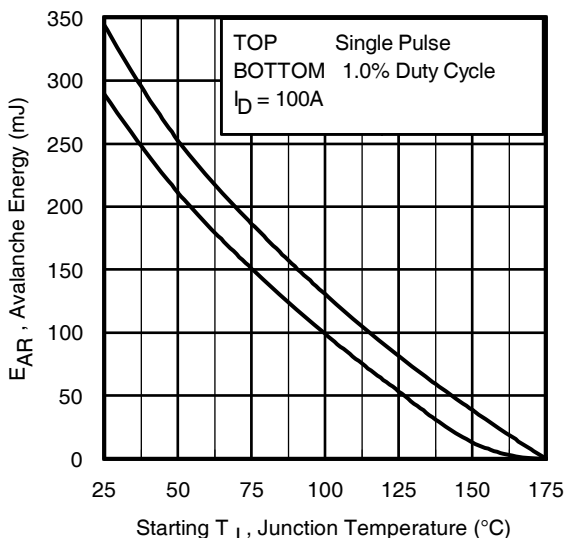


Fig 12. Maximum Avalanche Energy vs. Drain Current

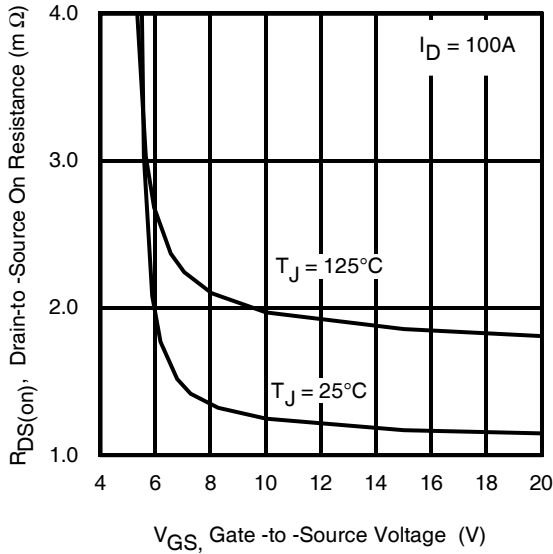
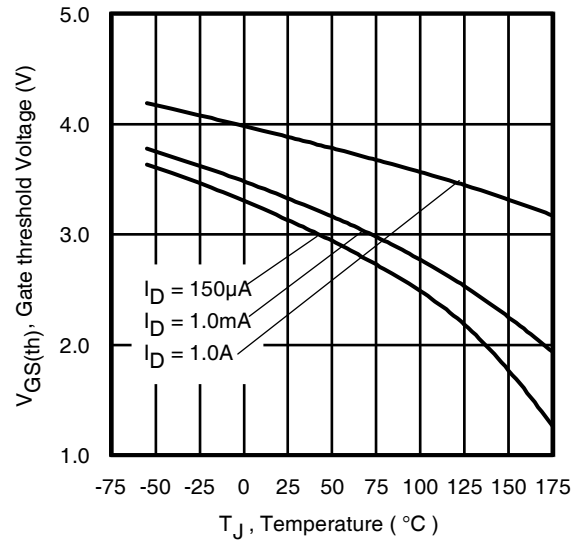
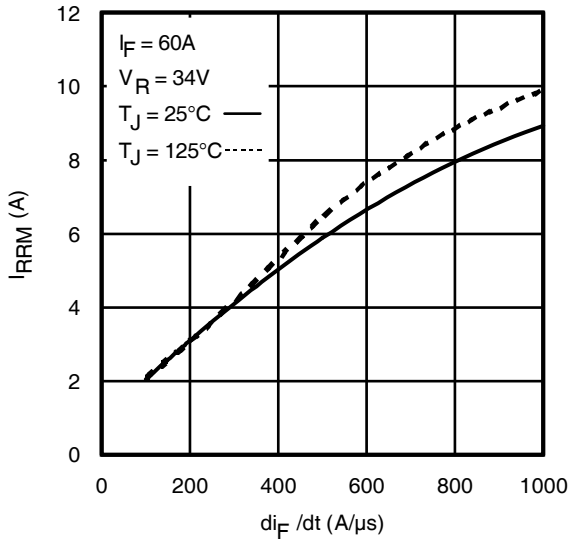
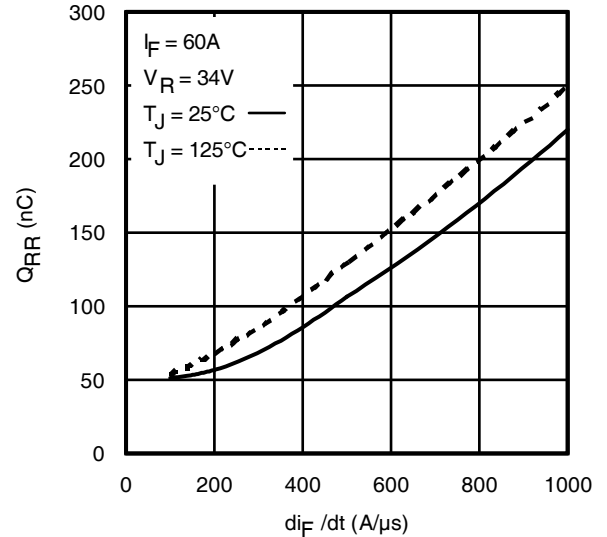
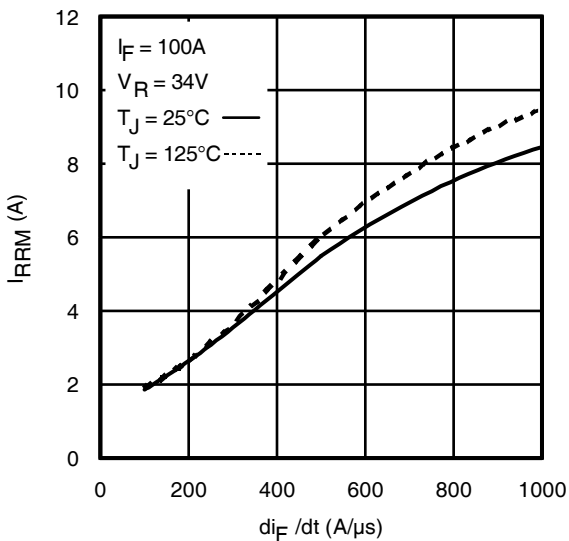
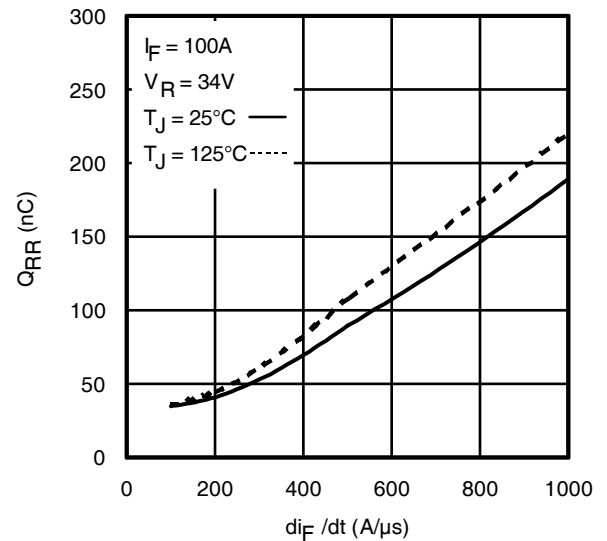

Fig 13. Maximum Effective Transient Thermal Impedance, Junction-to-Case

Fig 14. Typical Avalanche Current vs. Pulsewidth

Fig 15. Maximum Avalanche Energy vs. Temperature
**Notes on Repetitive Avalanche Curves , Figures 14, 15
(For further info, see AN-1005 at www.irf.com)**

1. Avalanche failures assumption:
Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax} . This is validated for every part type.
2. Safe operation in Avalanche is allowed as long as T_{jmax} is not exceeded.
3. Equation below based on circuit and waveforms shown in Figures 24a, 24b.
4. $P_{D(ave)}$ = Average power dissipation per single avalanche pulse.
5. BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
6. I_{av} = Allowable avalanche current.
7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 14, 15).
 t_{av} = Average time in avalanche.
 D = Duty cycle in avalanche = $t_{av} \cdot f$
 $Z_{thJC}(D, t_{av})$ = Transient thermal resistance, see Figures 13)

$$P_{D(ave)} = 1/2 (1.3 \cdot BV \cdot I_{av}) = \Delta T / Z_{thJC}$$

$$I_{av} = 2\Delta T / [1.3 \cdot BV \cdot Z_{th}]$$

$$E_{AS(AR)} = P_{D(ave)} \cdot t_{av}$$


Fig 16. On-Resistance vs. Gate Voltage

Fig 17. Threshold Voltage vs. Temperature

Fig. 18 - Typical Recovery Current vs. di_T/dt

Fig. 19 - Typical Stored Charge vs. di_T/dt

Fig. 20 - Typical Recovery Current vs. di_T/dt

Fig. 21 - Typical Stored Charge vs. di_T/dt

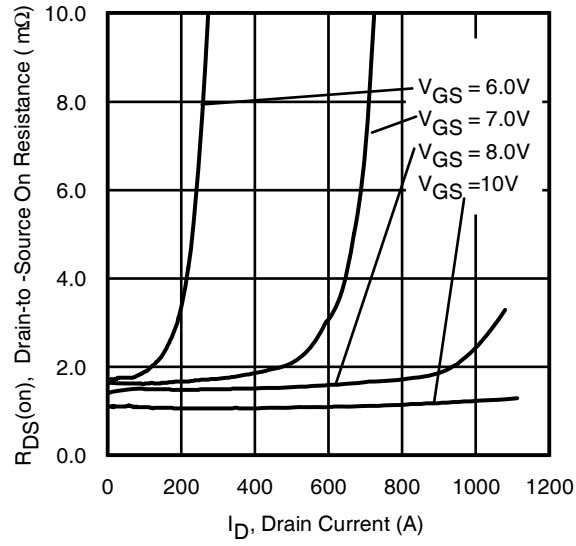
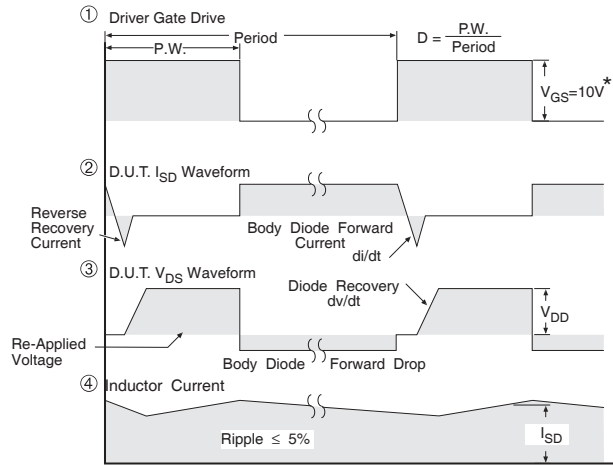
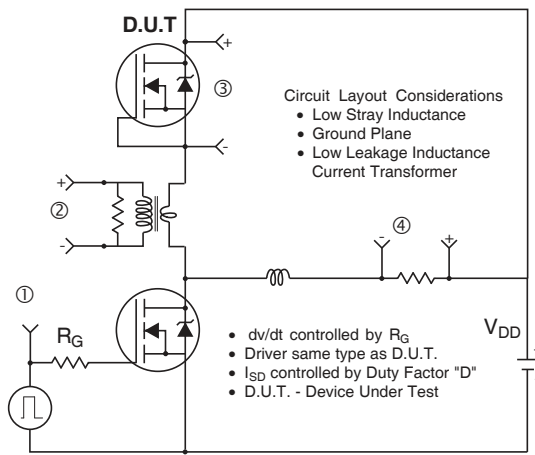


Fig 22. Typical On-Resistance vs. Drain Current



* $V_{GS} = 5V$ for Logic Level Devices

Fig 23. Peak Diode Recovery dv/dt Test Circuit for N-Channel HEXFET[®] Power MOSFETs

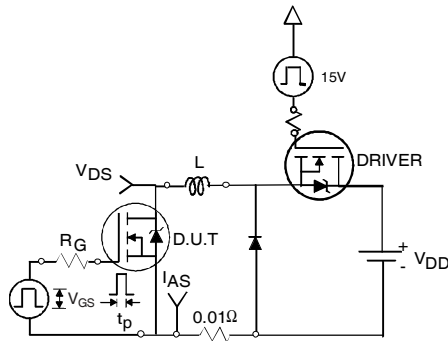


Fig 24a. Unclamped Inductive Test Circuit

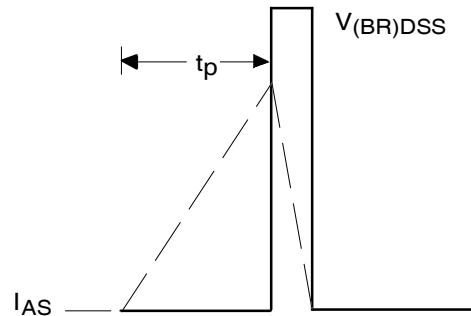


Fig 24b. Unclamped Inductive Waveforms

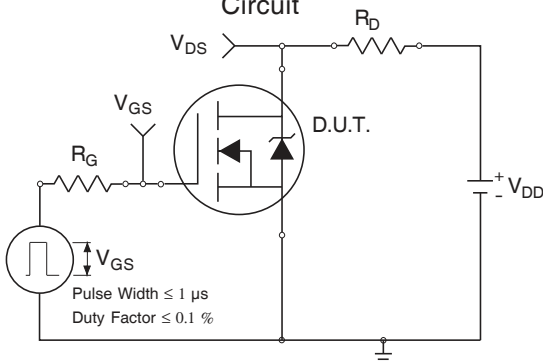


Fig 25a. Switching Time Test Circuit

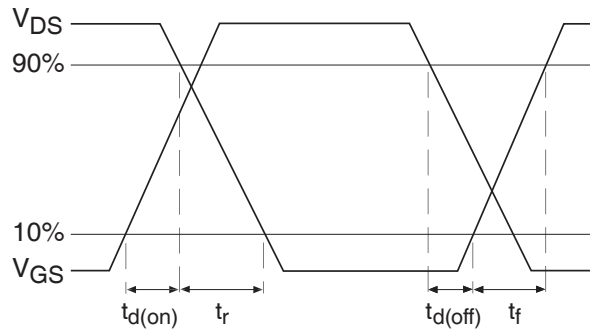


Fig 25b. Switching Time Waveforms

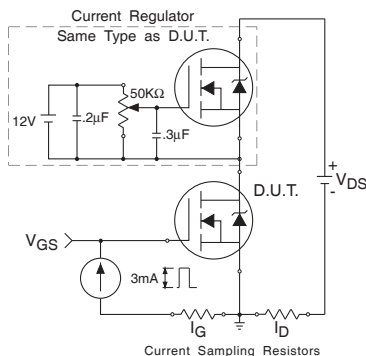


Fig 26a. Gate Charge Test Circuit

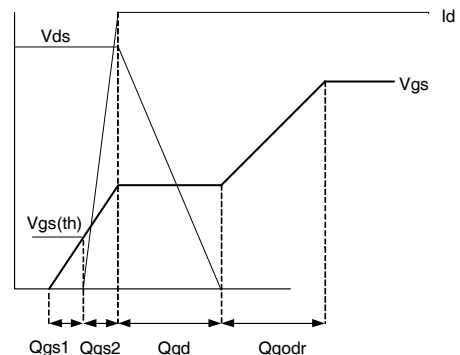


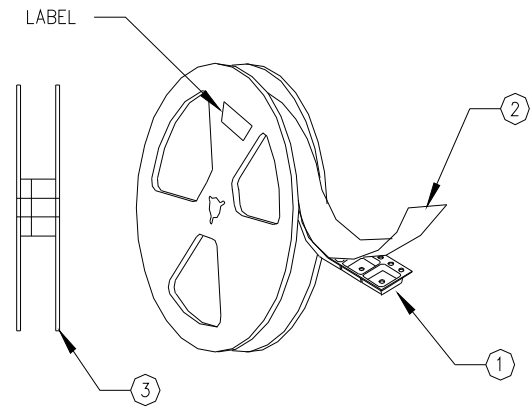
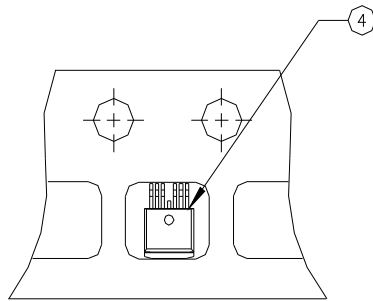
Fig 26b. Gate Charge Waveform

D²Pak - 7 Pin Tape and Reel

NOTES, TAPE & REEL, LABELLING:

1. TAPE AND REEL.
 - 1.1 REEL SIZE 13 INCH DIAMETER.
 - 1.2 EACH REEL CONTAINING 800 DEVICES.
 - 1.3 THERE SHALL BE A MINIMUM OF 42 SEALED POCKETS CONTAINED IN THE LEADER AND A MINIMUM OF 15 SEALED POCKETS IN THE TRAILER.
 - 1.4 PEEL STRENGTH MUST CONFORM TO THE SPEC. NO. 71-9667.
 - 1.5 PART ORIENTATION SHALL BE AS SHOWN BELOW.
 - 1.6 REEL MAY CONTAIN A MAXIMUM OF TWO UNIQUE LOT CODE/DATE CODE COMBINATIONS. REWORKED REELS MAY CONTAIN A MAXIMUM OF THREE UNIQUE LOT CODE/DATE CODE COMBINATIONS. HOWEVER, THE LOT CODES AND DATE CODES WITH THEIR RESPECTIVE QUANTITIES SHALL APPEAR ON THE BAR CODE LABEL FOR THE AFFECTED REEL.

2. LABELLING (REEL AND SHIPPING BAG).
 - 2.1 CUST. PART NUMBER (BAR CODE): IRFXXXXSTRL-7P
 - 2.2 CUST. PART NUMBER (TEXT CODE): IRFXXXXSTRL-7P
 - 2.3 I.R. PART NUMBER: IRFXXXXSTRL-7P
 - 2.4 QUANTITY:
 - 2.5 VENDOR CODE: IR
 - 2.6 LOT CODE:
 - 2.7 DATE CODE:



Qualification Information[†]

Qualification Level		Automotive (per AEC-Q101)	
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.	
		D ² PAK 7 Pin	MSL1
ESD	Machine Model	Class M3 (+/- 400V) ^{††} AEC-Q101-002	
	Human Body Model	Class H2 (+/- 4000V) ^{††} AEC-Q101-001	
	Charged Device Model	Class C5 (+/- 2000V) ^{††} AEC-Q101-005	
RoHS Compliant		Yes	

[†] Qualification standards can be found at International Rectifier's web site: <http://www.irf.com/>

^{††} Highest passing voltage.

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IR warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with IR’s standard warranty. Testing and other quality control techniques are used to the extent IR deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

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<http://www.irf.com/technical-info/>

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